

This is an RFQ (Request for Quote) for Supply of resists and related chemicals to be used for microelectronics applications (Quotes from Domestic manufacturers / vendors only).

## **Procedure:**

- 1. Vendors will be required to submit a quote containing details of the Indian OEM with FOR IISc Bengaluru price in INR only.
- 2. The technical description should take into account the following requirements and information that has been provided:

Cl	0
Chemicals	Quantity
Photoresist and relevant chemicals	12 Litre(minimum supply
	capacity per year) for resist,
<b>Type</b> : Positive, Negative, Image Reversal (with minimum dark	primer
erosion)	60 Litre(minimum supply
<b>Wavelength(nm):</b> UV(365,375,390, 405) and DUV(248nm)	capacity per year) for each of
(with Absorption Spectra, Contrast Curve)	Developers, Removers and
<b>Developer:</b> TMAH based (for Residue free development)	Strippers
Bake Temperatures: 80 to 180C	**
<b>Thickness(um)</b> : 0.5 to 1.5 (with Spin Curve, Uniformity, <3%	
on 4" wafer)	
<b>Resist Profile</b> :85 to 90 degree(with a good control on angle)	
<b>Adhesion</b> : Self to Si,SiO2, Pt (i.e resist should have good adhesion	
with with Semiconductors, Insulators and metals)	
Primer: Self HMDS, LOR or any customized	
<b>Removers/Strippers:</b> Non Toxic Room temperature to <80C	
Etch Resistance: Dry Etch Selectivity (1:1) or better	
with F, Cl, O2 and Wet etch resistance compatibility	
Shelf Life: Minimum 6 Months(12 months preferred)	
<b>Resolution(um)</b> : UV 0.5um to 1um, DUV(0.2 to 0.8)	
Exposure Dose: >5mJ/cm2	
Relevant Documents: MSDS, TDS	
eBeam Resist and relevant chemicals	6 Litre(minimum supply
esecuni resisti ana reteranti enemicats	capacity per year) for
<b>Type</b> : Positive, Negative; (with minimum dark erosion)	resist,primer
<b>Developer:</b> TMAH based (for Residue free development)	30 Litre(minimum supply
Bake Temperatures: 80 to 200C	capacity per year) for each of
Thickness(um): 0.05 to 0.5 (with Spin Curve, Uniformity, <3%)	Developers, Removers and
(with opin on ve, officially, 1970)	Developers, Removers and



on 4" wafer) **Strippers Resist Profile:**85 to 90 degree(with a good control on angle) Adhesion: Self to Si,SiO2, Pt (i.e resist should have good adhesion with with Semiconductors, Insulators and metals) **Primer:** Self HMDS, LOR or any customized **Removers/Strippers:** Non Toxic Room temperature to <80C **Etch Resistance**: Dry Etch Selectivity (1:1) or better with F, Cl, O2 and Wet etch resistance compatibility **Shelf Life:** Minimum 6 Months(12 months preferred) Resolution(um): 0.010um to 1um **Exposure Dose:** >100mJ/cm2 Relevant Documents: MSDS, TDS UV NIL and relevant chemicals 12 Litre(minimum supply capacity per year) for Type: UV, DUV(248nm) resist,primer Wavelength(nm):325,365, 405and DUV(248nm) 60 Litre(minimum supply (with Absorption Spectra, Contrast Curve) capacity per year) for each of **Bake Temperatures**: 60 to 180C (room temperature imprint Removers and Strippers preferred) Thickness(um): 0.1 to 1 (with Spin Curve, Uniformity, <3% on 4" wafer) **Adhesion**: Self to Si,SiO2, Pt (i.e resist should have good adhesion with Semiconductors, Insulators and metals) with Primer: Self mr APS1,LOR compatible or any customized **Removers/Strippers:** Non Toxic, Room temperature to <80C, O2 ashing **Etch Resistance**: Dry Etch Selectivity (1:1) or better with F, Cl, O2 and Wet etch resistance compatibility **Shelf Life:** Minimum 6 Months(12 months preferred) Resolution(um): 0.020um to 1um (and also upto 100um) **Exposure Dose:**  $>10 \text{mJ/cm}^2$ PDMS, Quartz Fused Silica (with excellent stamp **Stamps**: release properties) **Imprint Pressure**: 1 to 2 MPa (wider range preferred) Relevant Documents: MSDS, TDS Thermal NIL and relevant chemicals 12 Litre(minimum supply capacity per year) for Glass Transition(Tg):35C to 100C (No Tg after imprinting, i.e. resist,primer higher thermal stability) 60 Litre(minimum supply **Bake Temperatures**: 60 to 180C capacity per year) for each of Imprint Temperatures: 100C to 200C, Release temperatures 30C to Removers and Strippers

+91-80-2293-3342 E shankarks@iisc.ac.in http://www.cense.iisc.ac.in/shankar-kumar-selvarai



90C

Thickness(um): 0.1 to 1 (with Spin Curve, Uniformity, <3%

on 4" wafer)

Adhesion: Self to Si,SiO2, Pt (i.e resist should have good adhesion

with with Semiconductors, Insulators and metals) mr APS1,LOR compatible or any **Primer:** Self

customized

**Removers/Strippers:** Non Toxic, Room temperature to <80C, O2

ashing

**Etch Resistance**: Dry Etch Selectivity (1:1) or better

with F, Cl, O2 and Wet etch resistance compatibility

**Shelf Life:** Minimum 6 Months(12 months preferred)

Resolution(um): 0.020um to 1um (and also upto 100um) PDMS, Quartz Fused Silica (with excellent stamp **Stamps**:

release properties)

**Imprint Pressure**: 20 to 3000 Newton (wider range preferred)

**Relevant Documents: MSDS, TDS** 

- 3. The commercial comparison will be done as per Government of India rules, specifically GFR 2017. Note that GFR has recently been amended.
- 4. As per recent edits to the GFR, there are three classes of vendors distinguished by their "local content". In the cover letter, vendors must mention which applies to them: Class 1 supplier: Goods and services have a local content of equal to or more than 50%

Class 2 supplier: Goods and services have a local content more than 20% but less than 50%

Non-local supplier: Goods and services have a local content of equal to or less than 20%

- **5.** Quotes will be entertained from Class 1 or Class 2 suppliers only.
- 6. The deadline for submission of quotes is the 23<sup>rd</sup> July 2021, 5:30 pm Indian Standard Time. Proposals should arrive at the NNFC office, GF-20, Centre for Nano Science and Engineering, Indian Institute of Science, Bangalore 560012, India, by the above deadline



7. Please note: GST applicable to IISc will be 5 %. GST concessional certificate will be provided.

Thanking you,

Shankar Kumar Selvaraja, Ph.D.

Associate Professor

Centre for Nano Science and Engineering

Indian Institute of Science, Bangalore, India 560012.

Cell : +91-94-8128-3513 Office : +91-80-2293-3342 E-mail: shankars at iisc.ac.in